



OVERVIEW AND INSIGHT

**RESILIENCE ACROSS THE
EDUCATION ECOSYSTEM
DURING THE COVID-19 PANDEMIC**

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ACKNOWLEDGMENTS

Special thanks are given to the following reviewers of this paper:

- Mindel van de Laar, Maastricht University, Netherlands
- Afzal Hossain Sarwar, a2i, Government of Bangladesh, Bangladesh
- Binod Basnet, Educating Nepal, Nepal
- Bong-Keun Jung, Seoul National University, Republic of Korea
- Muhammad Aminu Ahmad, Kaduna State University, Nigeria
- Sunghee Chung, Chinese University of Hong Kong, Hong Kong
- Sarah Pinnock, Luton Borough Council, United Kingdom

The Institute of Electrical and Electronics Engineers, Inc. 3 Park Avenue, New York, NY 10016-5997, USA

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PDF: STDVA25845 978-1-5044-9288-1

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